

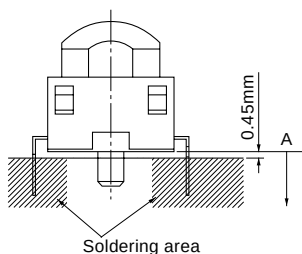
Tilt Sensor for Optical Disk

1. With built-in lens
2. Compact
3. Linear output current can be obtained in conformance with tilt angle.

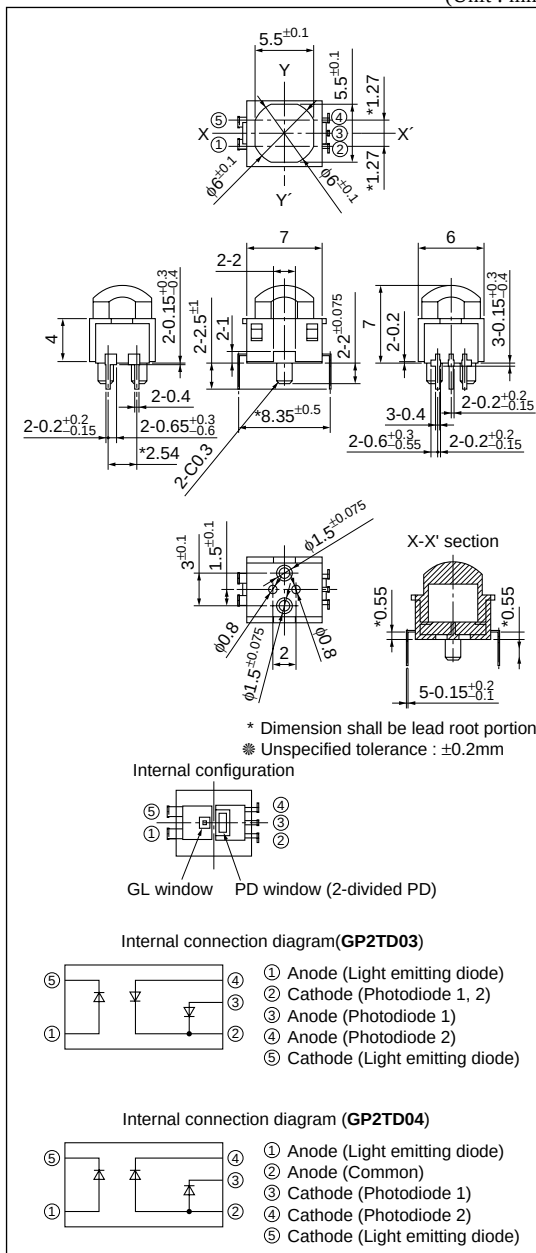
1. LD players
2. DVD players

Parameter		Symbol	Rating	Unit
Input	Forward current	I_F	50	mA
	Reverse voltage	V_R	6	V
	Power dissipation	$P_{D(IN)}$	75	mW
Output	Reverse voltage	V_R	20	V
	Power dissipation	$P_{D(OUT)}$	75	mW
Operating temperature		T_{opr}	-10 to +70	°C
Storage temperature		T_{stg}	-40 to +85	°C
*1 Soldering temperature		T_{sol}	260	°C

*1 For 5s below the tie bar cut part (0.45mm from the face A).



(Unit : mm)



■ Electro-optical Characteristics

(Ta=25°C)

Parameter		Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input (Emitter)	Forward voltage	V_F	$I_F=17\text{mA}$	—	1.25	1.5	V
	Reverse current	I_R	$V_R=6\text{V}$	—	—	10	μA
	Peak sensitivity wavelength	λ_{p1}	—	—	950	—	nm
	Spectrum radiation bandwidth	$\Delta\lambda$	—	—	45	—	nm
Output (Detector)	*2 Dark current (Each PD)		I_d	$V_R=10\text{V}$	—	—	100 nA
	Peak sensitivity wavelength	GP2TD03	λ_{p2}	—	960	—	nm
		GP2TD04	λ_{p2}	—	900	—	nm
	Response time	GP2TD03	t_r, t_f	*2 $V_R=1\text{V}, R_L=1\text{k}\Omega$		50	ns
		GP2TD04	t_r, t_f	*2 $V_R=1\text{V}, R_L=1\text{k}\Omega$		300	ns
	Short circuit current	GP2TD03	I_{SC}	*3 $E_V=1\ 000\ 1x$		4.2	μA
		GP2TD04	I_{SC}	*3 $E_V=1\ 000\ 1x$		3.5	μA
Coupling charac- teristics	*4 Difference output increment rate	GP2TD03	A/deg.	*4 $V_{CC}=5\text{V}, H=10.0\text{mm}, \theta_y=-0.5$ to 0 to $+0.5\text{deg.}$		3.3	$\mu\text{A/deg.}$
		GP2TD04	A/deg.	*4 $V_{CC}=5\text{V}, H=10.0\text{mm}, \theta_y=-0.5$ to 0 to $+0.5\text{deg.}$		3	$\mu\text{A/deg.}$
	*5 Angle range of tilt angle output 0	θ_0	*5 $V_{CC}=5\text{V}, H=10\text{mm}$		-2	—	+2 deg.
	*6 Monotonous increase range of tilt angle output	$ \theta_r $	*6 $V_{CC}=5\text{V}, H=10\text{mm}$		1.5	—	deg.
	*7 Non-invert range of tilt angle output	$ \theta_t $	*7 $V_{CC}=5\text{V}, H=10\text{mm}$		5.0	—	deg.
	*8 Leak	$ A_{LEAK} $	*8 $V_{CC}=5\text{V}$		—	—	57 nA

*2 Measuring method of response time, refer to Fig.1

*3 E_V : Illuminance by CIE standard light source A (tungsten lamp).*4 Difference output A stands for $A=I_{SC}(\text{PD1})-I_{SC}(\text{PD2})$.

Difference output increment rate (A/deg.) shall be the current increase rate of A for 1deg.

$$\frac{\{I_{SC}(\text{PD1})-I_{SC}(\text{PD2})\} \text{ at } (+0.5\text{deg.}) - \{I_{SC}(\text{PD2})-I_{SC}(\text{PD1})\} \text{ at } (-0.5\text{deg.})}{1}$$

*5 The subtraction output zero angle region shall be the range of the angle at which A is zero.

*6 The angle, θ_r , which monotonously increases when the angle at which A is zero is assumed to be zero.*7 The subtraction output non-reversing region shall be the angle, θ_t , when the angle which A is zero is assumed to be zero.*8 A_{LEAK} applies to the value of A measured without reflective object.

*9 The measurement of *4 to *8 shall be on test circuit in accordance with Fig.8 and Fig.9.

*10 Reflective object used in test for coupling characteristics shall be multi-layer coating mirror (NIPPON SHINKU KOGAKU made mirror of reflectance of 95% min. at 950nm).

The test circuit and the coordinate system shall be as shown in Fig.8 and Fig.9. It shall be assumed that there is no deviation in the directions X and Y.

Fig.1 Test Circuit for Response Time

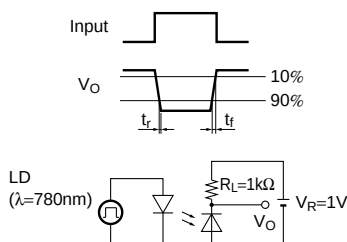


Fig.2 Subtraction Output

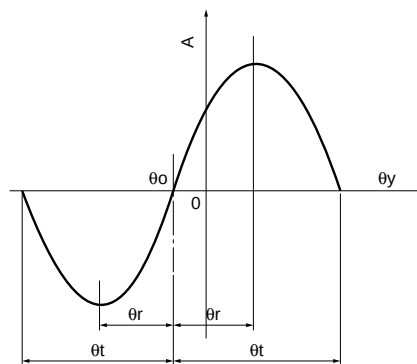
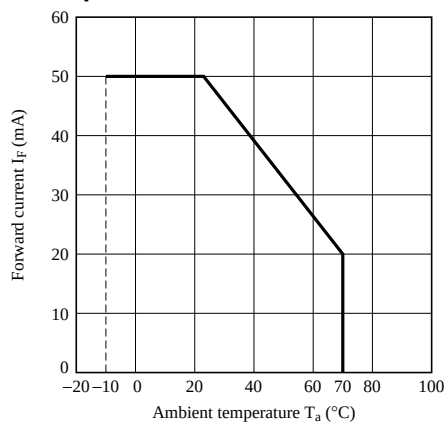
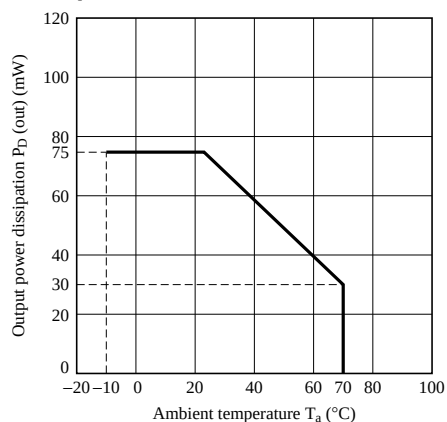
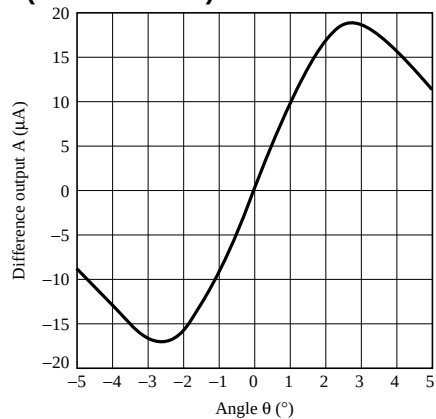
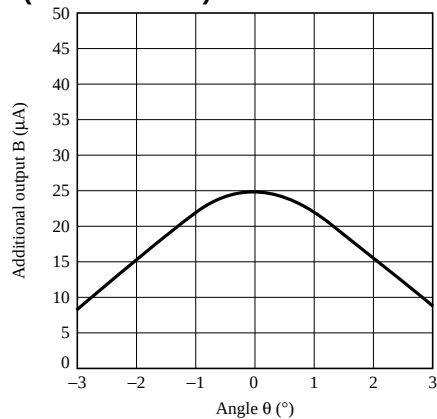
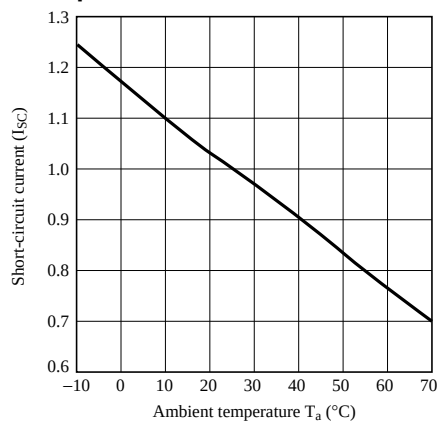


Fig.3 Forward Current vs. Ambient Temperature**Fig.4 Output Power Dissipation vs. Ambient Temperature****Fig.5 Difference Output vs. Angle (Y-Y' direction)****Fig.6 Additional Output vs. Angle (X-X' direction)****Fig.7 Short-circuit Current vs. Ambient Temperature**

GP2TD03

GP2TD04

The diagram shows a circuit for a photodiode sensor. It includes a +5V supply, a resistor R1, and a light source. The photodiode is connected to a non-inverting amplifier circuit. The amplifier consists of two operational amplifiers (op-amps) configured as a voltage follower and a non-inverting amplifier. The output of the non-inverting amplifier is connected to a load resistor R9. The circuit is powered by a +5V supply and a -15V supply. The photodiode is labeled GP2TD04. The output of the non-inverting amplifier is labeled +15 and -15. The circuit is labeled with various components: R1, R2, R3, R4, R5, R6, R7, R8, R9, and the op-amp chips.

Specifications above are calculated using output current.

Figure 1 consists of two schematic diagrams. Diagram (a) is a top view showing a square base with a central circular region. Four photointerrupters are positioned around the base, labeled X, X', Y, and Y'. Diagram (b) is a side view showing a reflective object at a height H above the base. A vertical Z-axis and a horizontal X-axis are shown. The angle of reflection is labeled as $\theta = 0^\circ$.

Definition of $\theta=0^\circ$: Surface parallel to the reference plane A of this reflection type photointerrupter defined by the equation $Z=H$ ($H=10\text{mm}$) shall be taken as a $\theta=0^\circ$ surface. The clockwise direction of rotation of a reflective object located at $\theta=0^\circ$ around the X-axis shall be the $\theta(+)$ rotational direction. The counterclockwise direction of its rotation shall be the $\theta(-)$ rotational direction.

■ Precautions for Use

1. Cleaning

Polycarbonate resin is used as the material of the lens surface. As to cleaning, this reflective type photointerrupter shall not be cleaned by cleaning materials absolutely. Dust and stain shall be cleaned by air blow, or shall be cleaned by soft cloth soaked in washing materials.

2. Reduction of light emitting diode output

In circuit designing, make allowance for the degradation of the light emitting diode output that results from long continuous operation. (50% degradation / 5years)

3. Soldering

To solder onto lead pins, solder at the position of 0.45mm or more from the package's bottom at 260°C for 5s or less. Please don't bend lead pins from the root of package when soldering. And please take care not to let any external force exert on lead pins. Please don't do soldering with preheating, and please don't do soldering by reflow.

4. Positioning pin

This reflection type photointerrupter is positioned in the directions X and Y of the coordinate system shown in Fig.9 by means of two $\phi 1.5$ mm pins of 2-mm height.

Do not heat stake the positioning pin because it affects the reliability of the internal element adversely. To fix the pin, use adhesives unlikely to erode this reflection type photointerrupter such as epoxy and silicone type adhesives.

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